

SPECIFICATION

REFOND P/N

RF-A4H40-W60P-E5

R&D

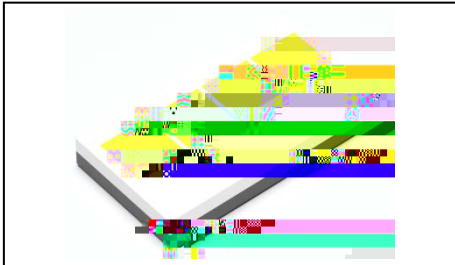
Mass Production

Contents

1. Description	3
1.1 General Description	3
1.2 Features	3
1.3 Application	3
1.4 Package Dimension	4
1.5 Product Parameters	5
1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=1000mA)	BIN
(IF=1000mA)	6
1.7 Typical Optical Characteristics Curves	8
2. Packaging	13
2.1 Packaging Specification	13
2.1.1 Carrier Tape Dimension	13
2.1.2 Reel Dimension	13
2.1.3 Label Form Specification	14
2.2 Moisture Resistant Packing	14
2.3 Cardboard Box	14
2.4 Reliability Test Items And Conditions	15
2.5 Criteria For Judging Damage	16
SMT Reflow Soldering Instructions SMT	17
3.1 SMT Reflow Soldering Instructions SMT	17
4. Handling Precautions	19
4.1 Handling Precautions	19

1. Description

1.1 General Description



The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:5.6mmX3.0mmX0.8mm.

LED

5.6mmX3.0mmX0.8mm

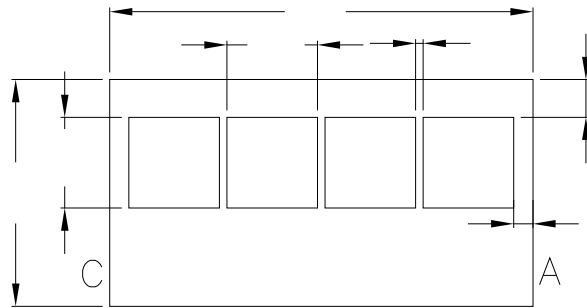
1.2 Features

- ▶ Ceramic Package.
- ▶ Extremely wide viewing angle.
- ▶ Suitable for all SMT assembly and solder process. SMT
- ▶ Available on tape and reel.
- ▶ Moisture sensitivity level: Level 2. Level2
- ▶ RoHS compliant. RoHS
- ▶ Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102 Stress Test Qualification for Automotive Grade Discrete Semiconductors AEC-Q102

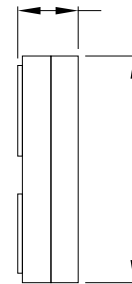
1.3 Application

- ▶ Automotive Lighting Exterior.

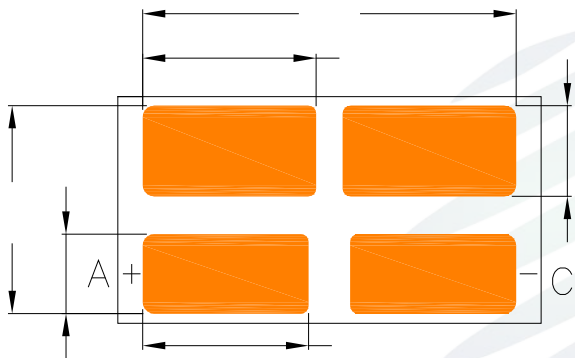
1.4 Package Dimension



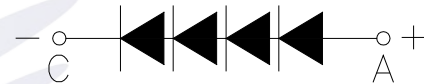
正面视图



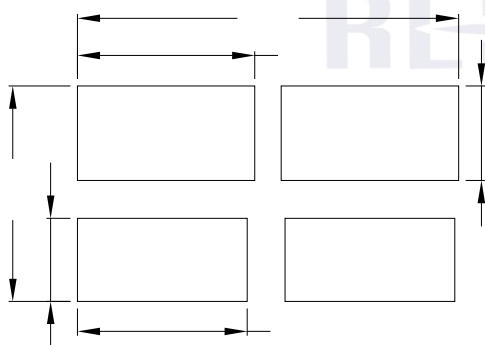
侧面视图



背面视图



极性



推荐焊盘

Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

± 0.2

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=1000\text{mA}$	11.2	---	14.4	V
Reverse Current	I_R	$V_R=20\text{V}$	---	---	10	μA

Table 1-2 Absolute Maximum Ratings at Ts=25°C



Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous flux measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
8. At 25 °C, pulse mode test, photoelectric conversion efficiency $\eta=43\%$. 25 °C
43%
9. Thermal resistance values (Rth JS Electrical) measure current is 1000mA, Temperature constant at 25°C.
(Rth JS Electrical) 1000mA 25°C

1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=1000mA)

BIN (IF=1000mA)

Table 1-3

V _F V	K1	D1	E1	F1
	11.2-12.0	12.0-12.8	12.8-13.6	13.6-14.4
φ lm	EA	EB	EC	ED
	1300-1450	1450-1600	1600-1750	1750-2000

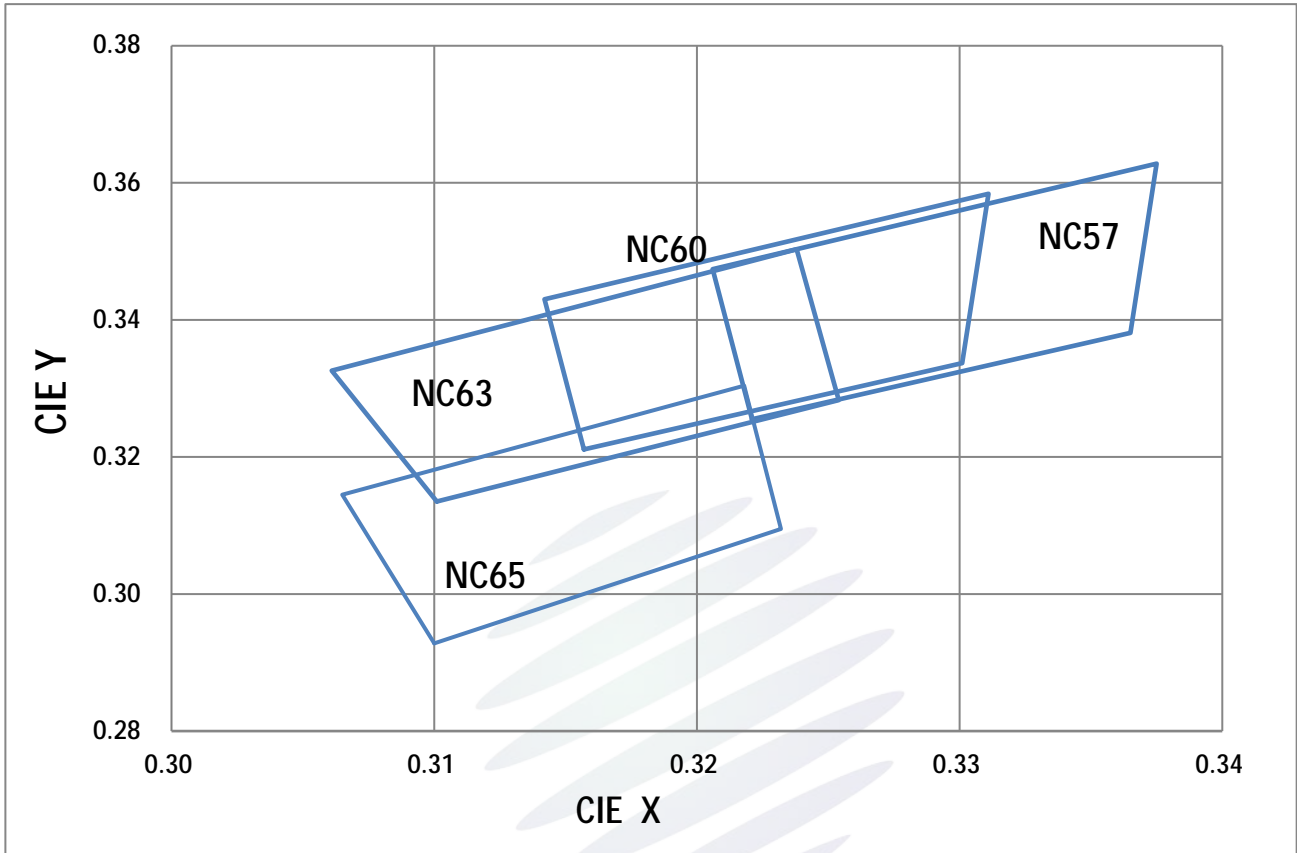


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
NC57	0.3221	0.3255	0.3206	0.3474	0.3375	0.3628	0.3365	0.3381
NC60	0.3157	0.3211	0.3142	0.3430	0.3311	0.3584	0.3301	0.3337
NC63	0.3101	0.3135	0.3061	0.3326	0.3238	0.3503	0.3254	0.3283
NC65	0.3100	0.2928	0.3065	0.3145	0.3218	0.3304	0.3232	0.3095

1.7 Typical Optical Characteristics Curves

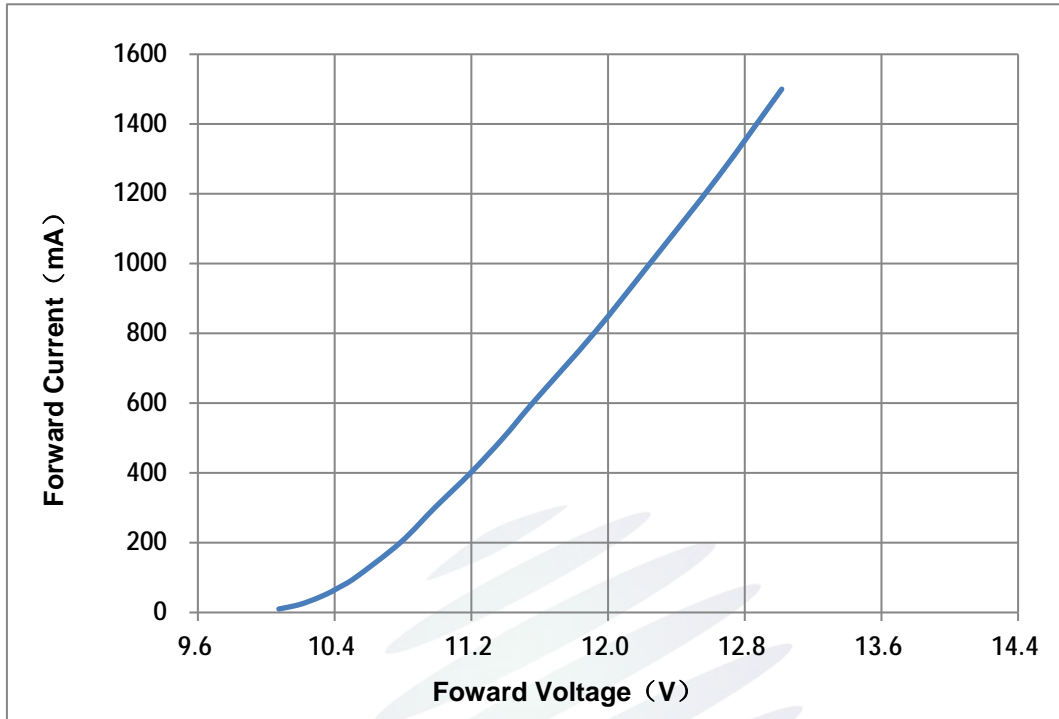


Fig. 1-7 Forward Voltage Vs Forward Current

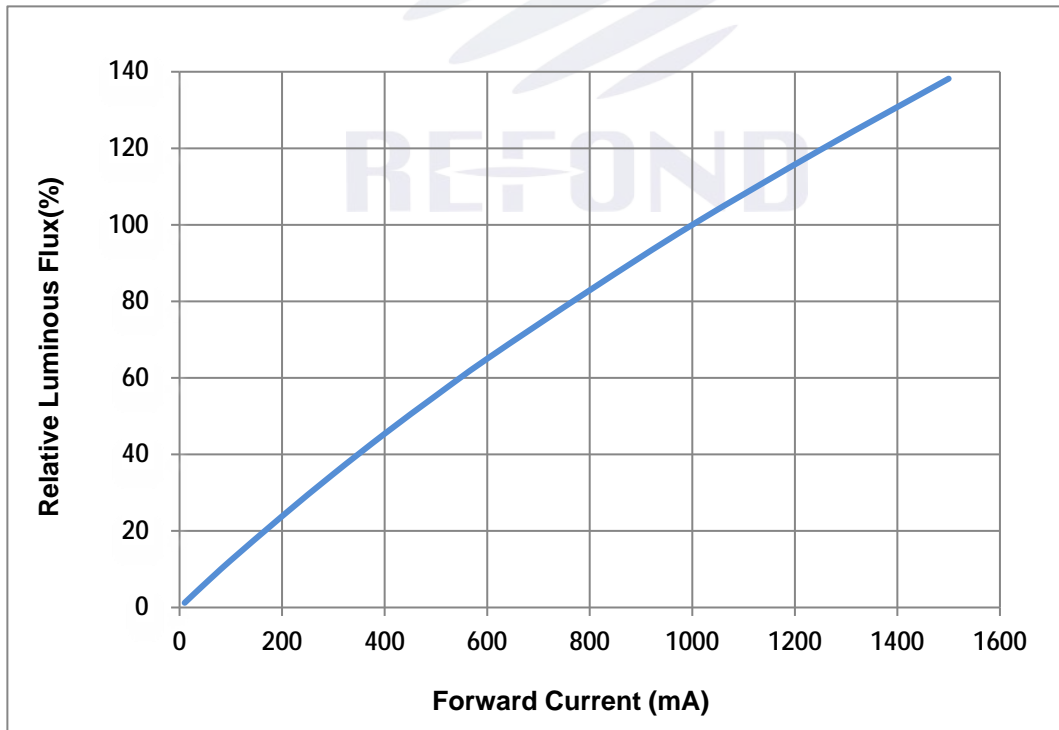


Fig. 1-8 Forward Current Vs Relative Intensity

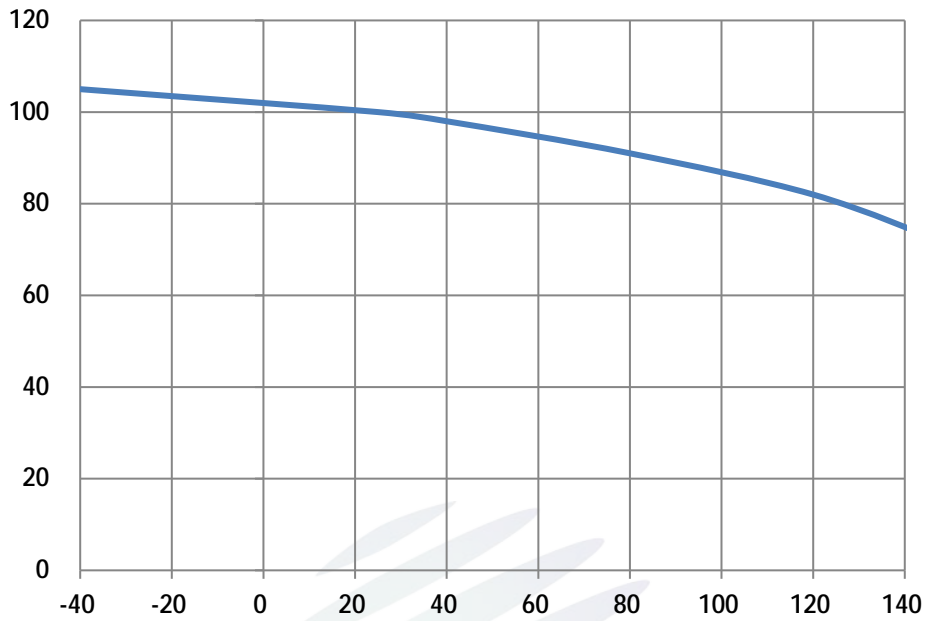


Fig. 1-9 Junction Temperature Vs Relative Intensity



Fig. 1-10 Solder Temperature Vs Forward Current

Tj 150

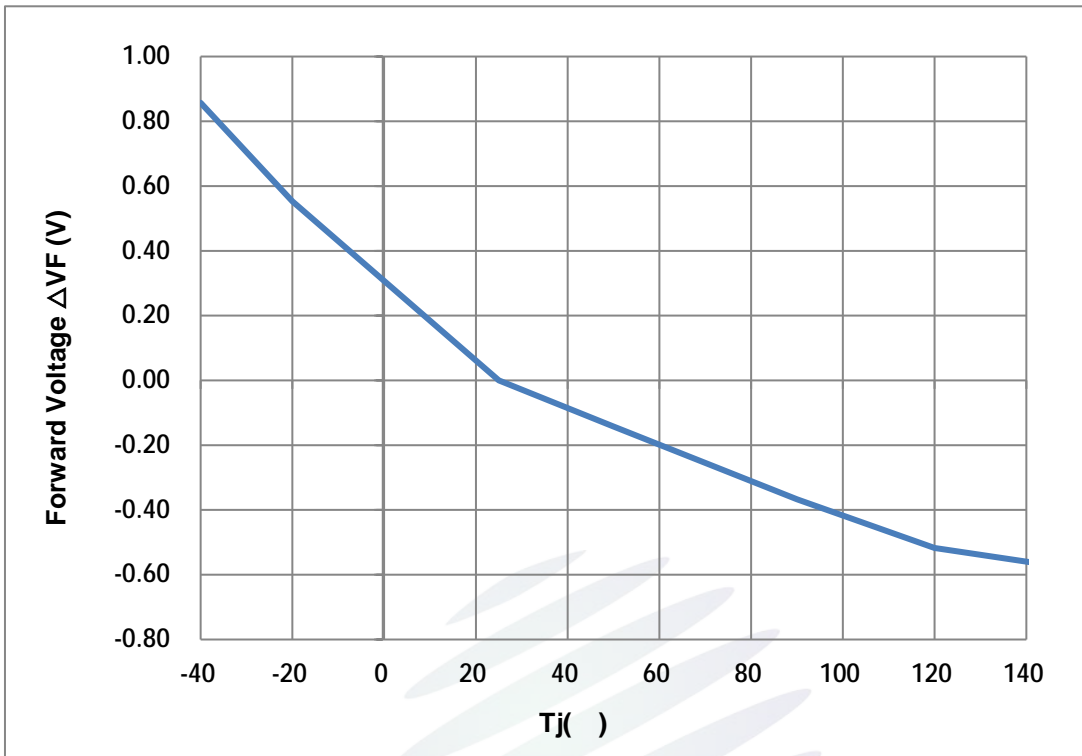


Fig. 1-11 Voltage Shift Vs Junction Temperature

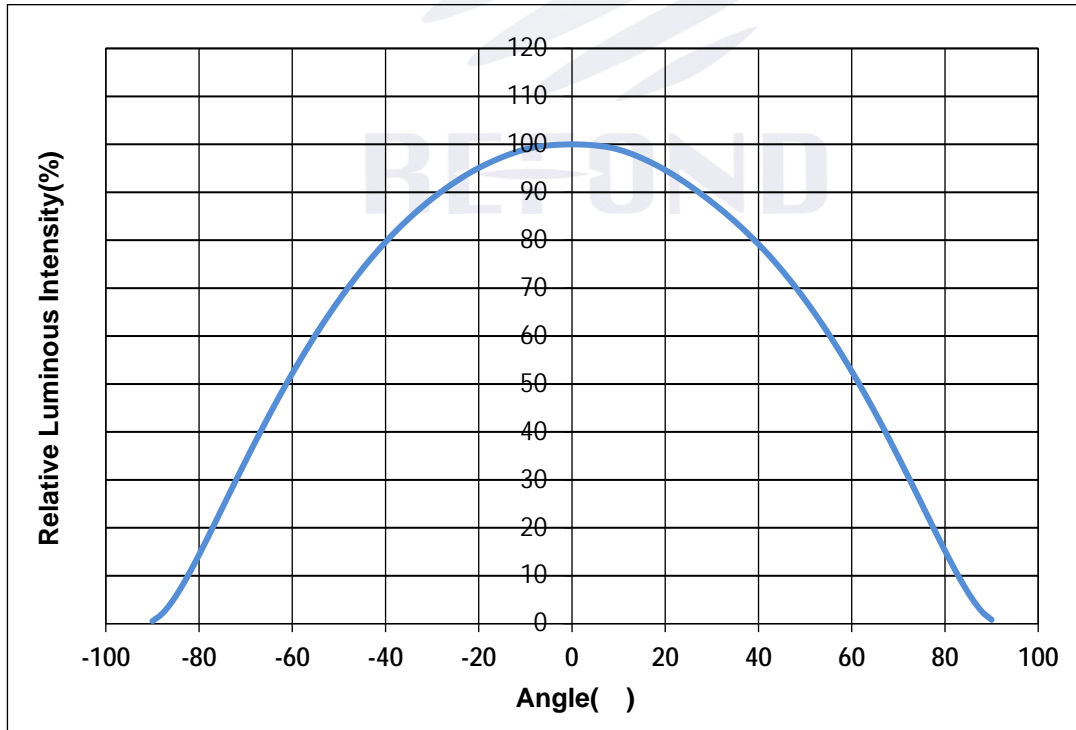


Fig. 1-12 Radiation diagram

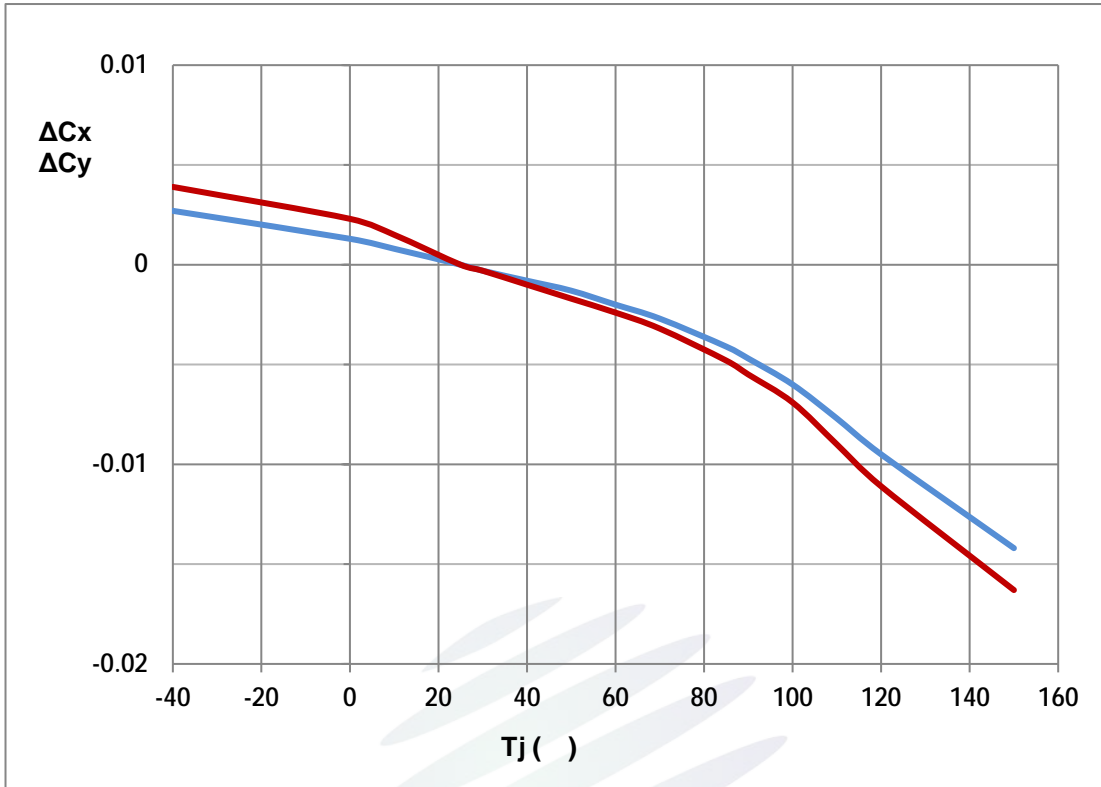


Fig. 1-13 Chromaticity Coordinate Shift Vs Junction Temperature

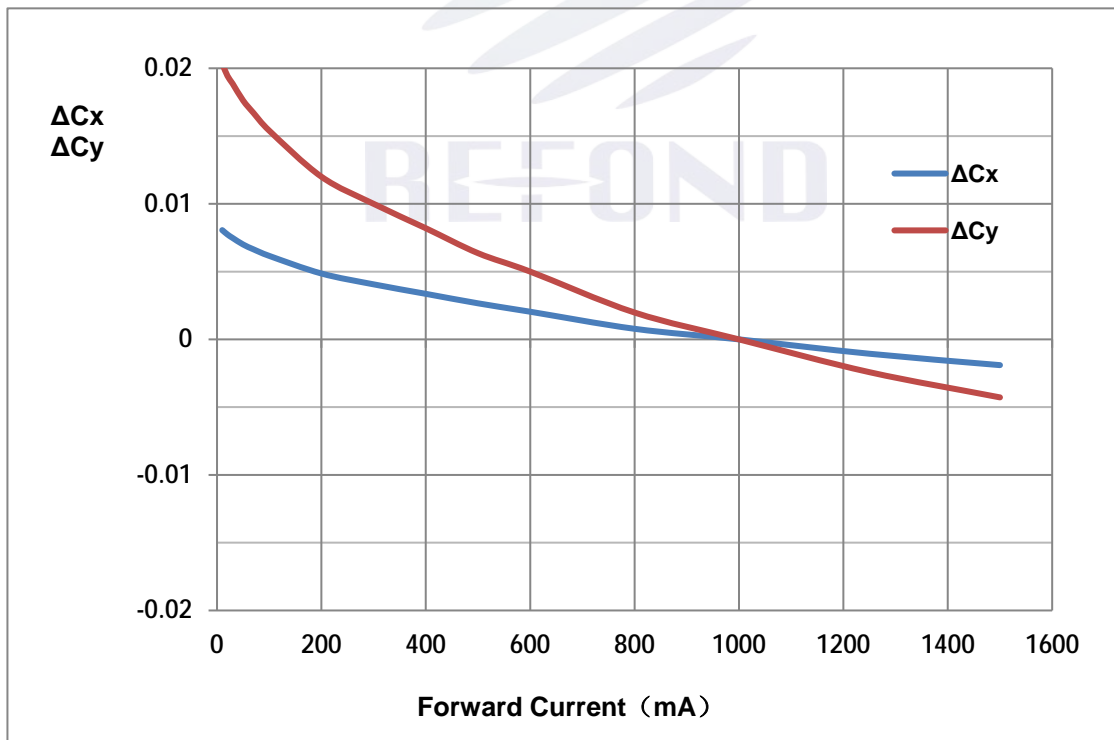


Fig. 1-14 Chromaticity Coordinate Shift Vs Forward Current

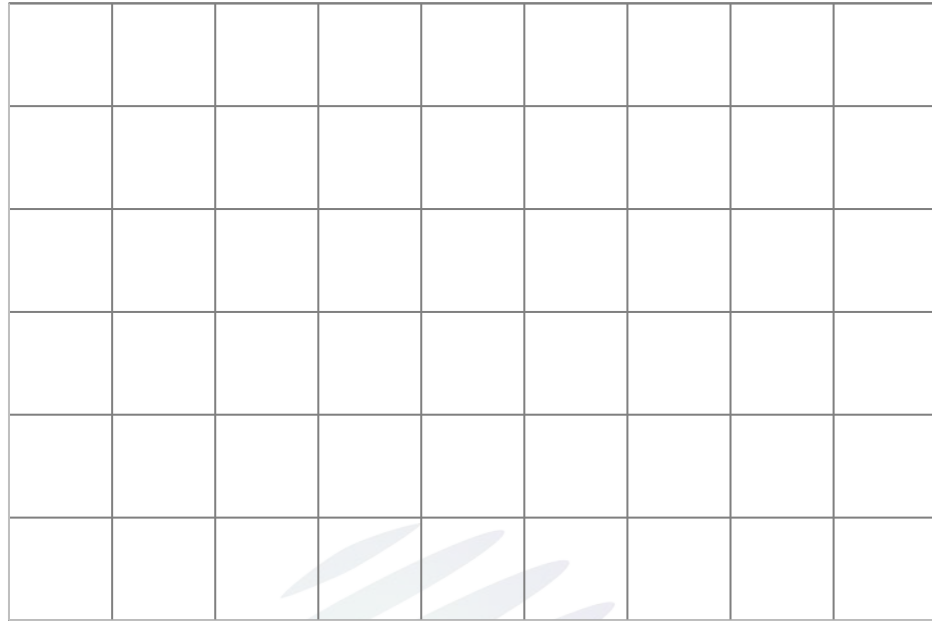


Fig 1-15 Spectrum Distribution

REFOND

2. Packaging

2.1 Packaging Specification

Package: 4000pcs/reel. 4000pcs

2.1.1 Carrier Tape Dimension

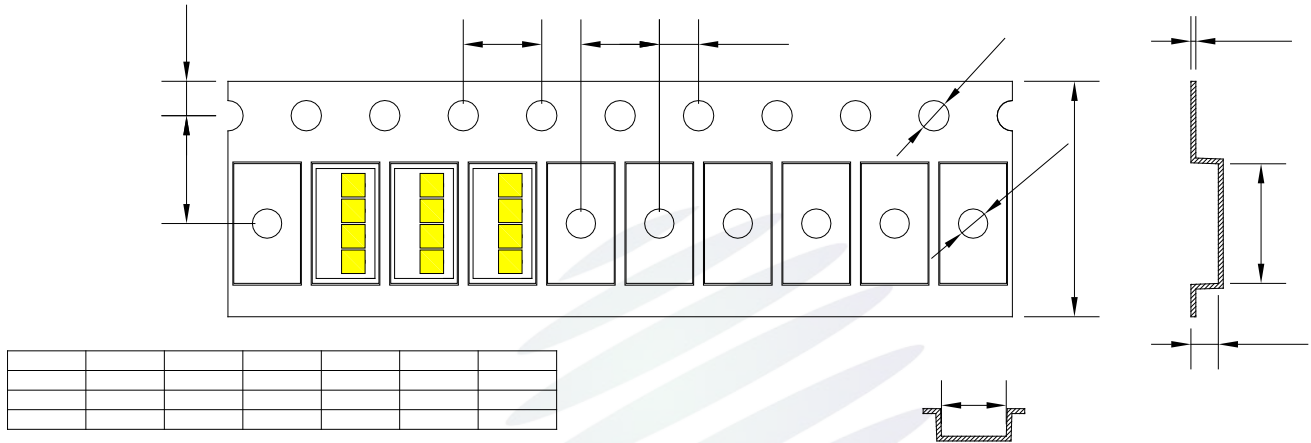


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

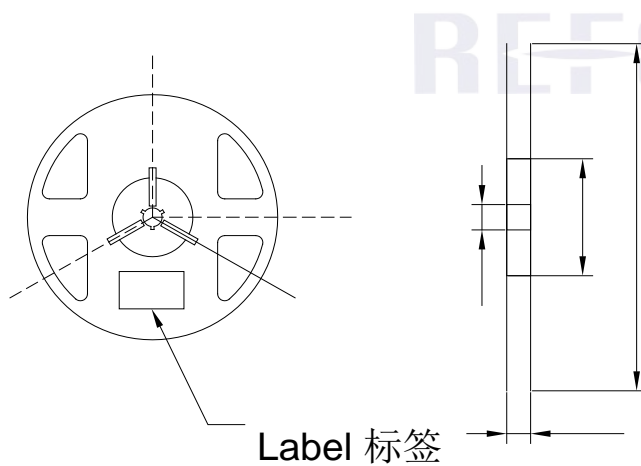


Fig.2-2 Reel Dimension

Table 2-1 Reel Dimension

A	13.6± 0.1mm
B	180± 1mm
C	100± 1mm
D	13.0± 0.5mm

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm

± 0.1

2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing



Fig.2-4 Moisture Resistant Packing

2.3 Cardboard Box

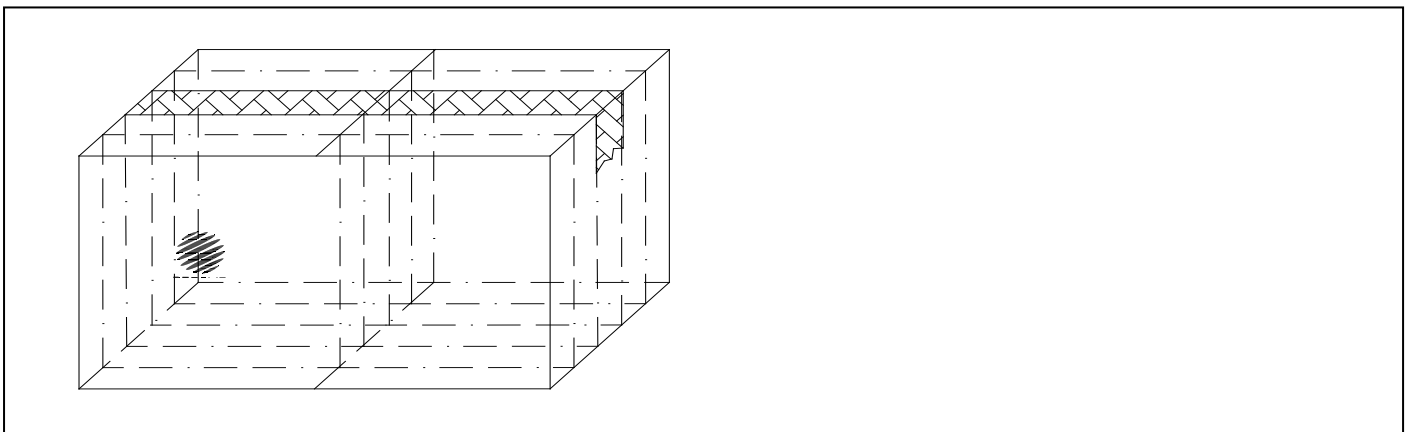


Fig.2- Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref. Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=120 If=1000mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH If=1000mA	1000hrs.	20pcs.	0/1

2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=1000\text{mA}$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R = 20\text{V}$	-	U.S.L*)x2.0
Luminous Flux	Φ	$I_F=1000\text{mA}$	L.S.L*)x0.7	-

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
2. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

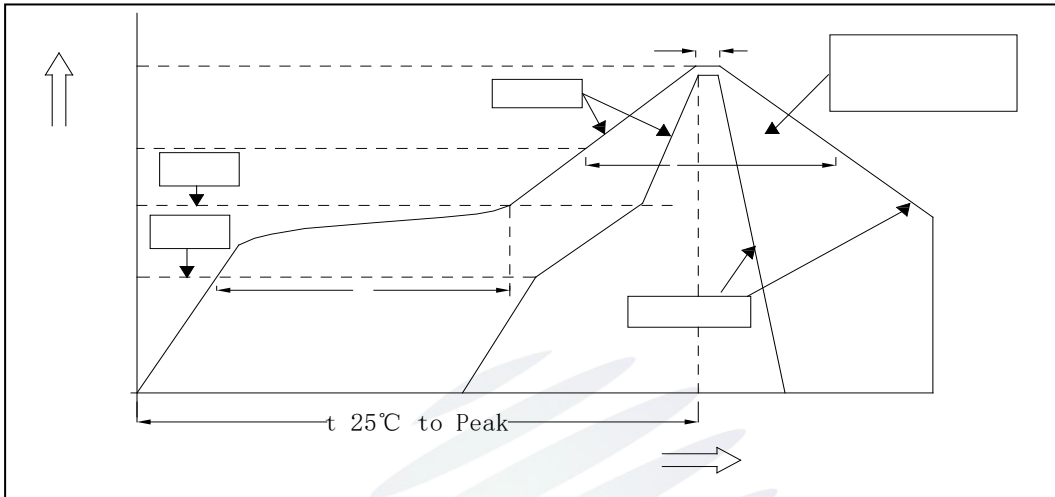


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	T_{smax}	T_P	3 °C/	Max 3 °C/ s
Preheating: minimum temperature	(T _{smin})		150 °C	
Preheating: Max temperature	(T _{smax})		200 °C	
Preheating: Time	T _{smin}	T _{smax}	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T _L)		217 °C	
Time limited to maintain high temperature: The Time	(t _L)		60	Max 60s
Peak /Classification of temperature:	/	(T _P)	260 °C	
Time limit classification of peak temperature time	t _p		10	Max 10s
(T _P) 5 °C	Hold time within 5 °C with the actual peak temperature (T _P)		30	Max 30s
Cooling speed			6 °C/	Max 6 °C/ s
25 °C	Needed time from 25 °C to T _p		8	Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 24 LED

(2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 R Bi 0 Tr () Ti 0 T (nCID 2 >>BDC /CO_0 1 Tf -0 Tc 0 Tw 8.086 0 Td <35105D284.7 Tw 0.5<295



4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

LED 100PPM

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

LED 900PPM 900PPM 1500PPM



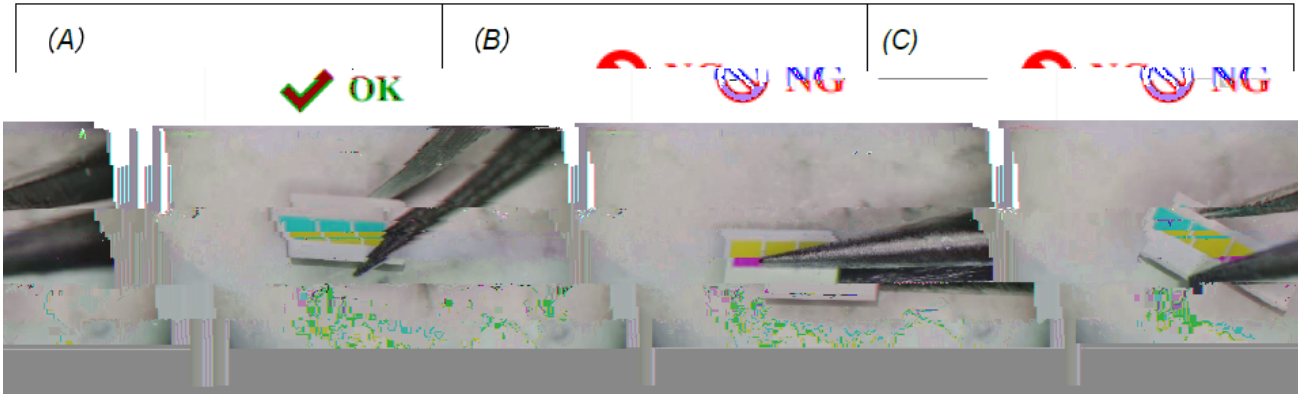


Fig 4-1 Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage 儲存	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24
Baking		60± 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 60±5 for above 24 hours.

60± 5 24

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED

(10) Other points for attention, please refer to our relevant information.



Declare

This specification is written both in English and in Chinese and the latter is formal.